

MOSFET - N-Channel QFET

250 V, 40 A, 70 m Ω

FQA40N25

Description

This N-Channel enhancement mode power MOSFET is produced using **onsemi**'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

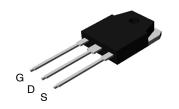
- 40 A, 250 V, $R_{DS(on)} = 70 \text{ m}\Omega$ (Max) @ $V_{GS} = 10 \text{ V}$, $I_D = 20 \text{ A}$
- Low Gate Charge (Typ. 85 nC)
- Low Crss (Typ. 70 pF)
- 100% Avalanche Tested
- This is a Pb-Free Device

ABSOLUTE MAXIMUM RATINGS

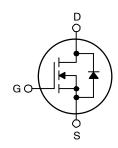
(T_C = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	250	V
I _D	Drain Current Continuous ($T_C = 25^{\circ}C$) Continuous ($T_C = 100^{\circ}C$)	40 25	Α
I _{DM}	Drain Current – Pulsed (Note 1)	160	Α
V_{GSS}	Gate to Source Voltage	±30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	800	mJ
I _{AR}	Avalanche Current (Note 1)	40	Α
E _{AR}	Repetitive Avalanche Energy (Note 1)	28	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.5	V/ns
P _D	Power Dissipation (T _C = 25°C) – Derate above 25°C	280 2.22	W W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
TL	Maximum Lead Temperature for Soldering Purposes, 1/8" from Case for 5 Seconds	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



TO-3P-3LD / EIAJ SC-65, ISOLATED CASE 340BZ



MARKING DIAGRAM

FQA 40N25 AYWWZZ

FQA40N25 = Specific Device Code
A = Assembly Location
YWW = Date Code (Year & Week)
ZZ = Assembly Lot

ORDERING INFORMATION

Device	Package	Shipping
FQA40N25	TO-3P (Pb-Free)	450 Unit / Tube

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case, Max	0.45	°C/W
$R_{\theta CS}$	Thermal Resistance, Junction-to-Sink, Typ	0.24	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max	40	°C/W

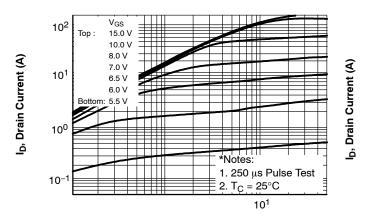
ELECTRICAL CHARACTERISTICS (T_C = 25°C, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHAR	ACTERISTIC		•			
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, D = 250 \mu\text{A}$	250	-	-	V
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	0.24	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 250 V, V _{GS} = 0 V	-	-	1	μΑ
		V _{DS} = 200 V, T _C = 125°C	-	-	10	
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	-	-	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	-100	
ON CHARA	CTERISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0	-	5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 20 A	-	0.051	0.07	Ω
9FS	Forward Transconductance	V _{DS} = 50 V, I _D = 20 A	-	29	-	S
OYNAMIC (CHARACTERISTICS					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,	-	3100	4000	pF
C _{oss}	Output Capacitance	f = 1.0 MHz	-	620	800	pF
C _{rss}	Reverse Transfer Capacitance		-	70	90	pF
SWITCHING	CHARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 125 V, I _D = 40 A,	-	70	150	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$ (Note 4)	-	580	1150	ns
t _{d(off)}	Turn-Off Delay Time		-	120	250	ns
t _f	Turn-Off Fall Time		-	165	340	ns
Q_g	Total Gate Charge	$V_{DS} = 200 \text{ V}, I_D = 40 \text{ A},$	-	85	110	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V (Note 4)	-	25	-	nC
Q_{gd}	Gate-Drain Charge		_	46	-	nC
DRAIN-SO	URCE DIODE CHARACTERISTICS AND N	MAXIMUM RATINGS				
I _S	Maximum Continuous Drain-Source Diode Forward Current		-	-	40	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	-	160	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 40 A	-	-	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 40 A,	-	220	-	ns
Q _{rr}	Reverse Recovery Charge	dl _F /dt = 100 A/μs	-	2.0	-	μС

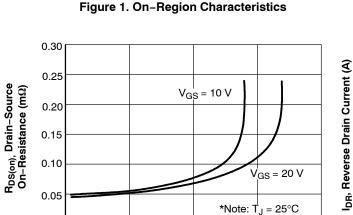
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Repetitive Rating: Pulse width limited by maximum junction temperature.
 L = 0.8 mH, I_{AS} = 40 A, V_{DD} = 50 V, R_G = 25 Ω, Starting T_J = 25°C.
 I_{SD} ≤ 40 A, di/dt ≤ 300 A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C.
 Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS



V_{DS}, Drain-Source Voltage (V)



0.00

I_D, Drain Current (A)

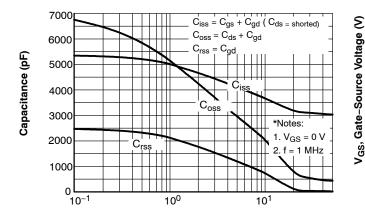
100

150

200

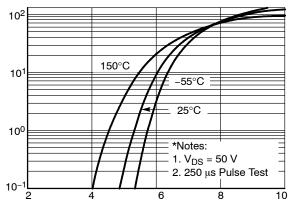
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Figure 3. On-Resistance Variation vs. Drain **Current and Gate Voltage**



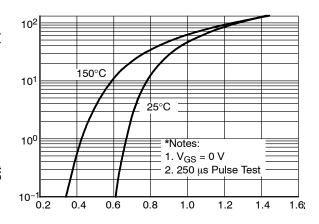
V_{DS}, Drain-Source Voltage (V)

Figure 5. Capacitance Characteristics



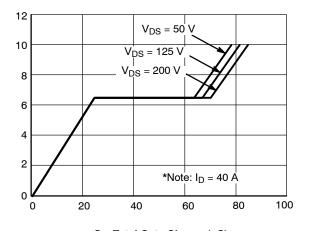
V_{GS}, Gate-Source Voltage (A)

Figure 2. Transfer Characteristics



V_{SD}, Body Diode Forward Voltage (V)

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



Q_q, Total Gate Charge (nC)

Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted) (continued)

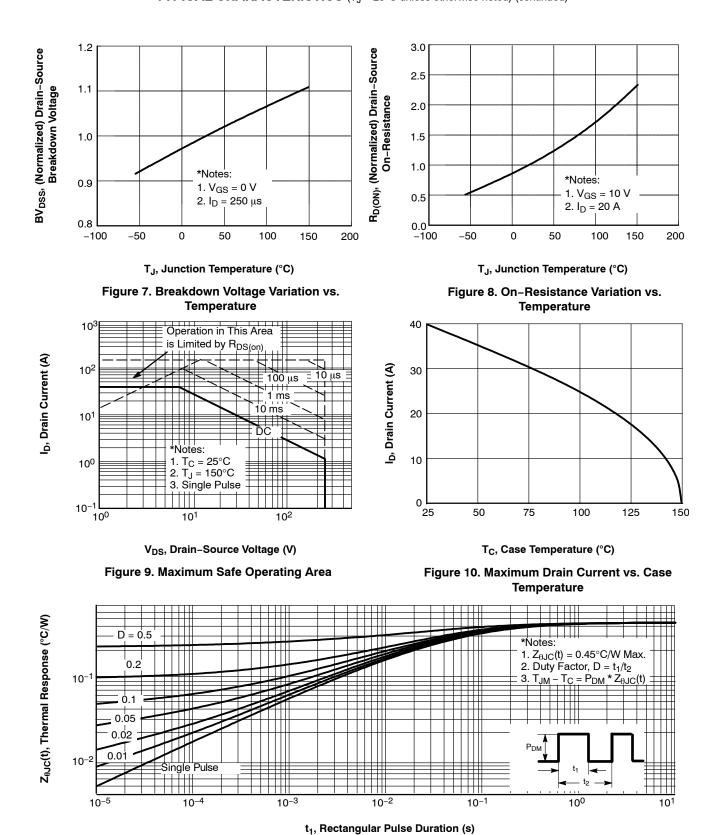


Figure 11. Transient Thermal Response Curve

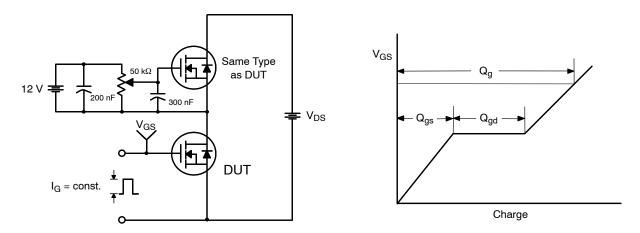


Figure 12. Gate Charge Test Circuit & Waveform

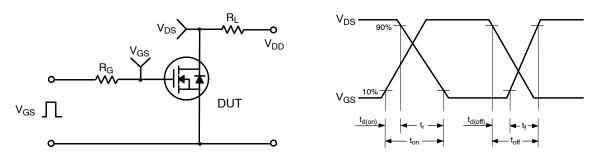


Figure 13. Resistive Switching Test Circuit & Waveforms

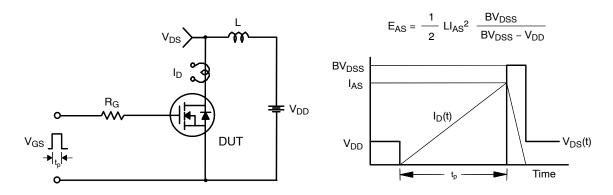
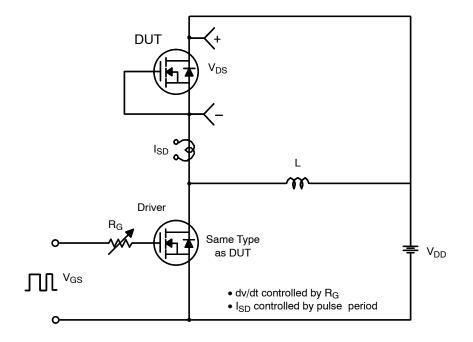


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



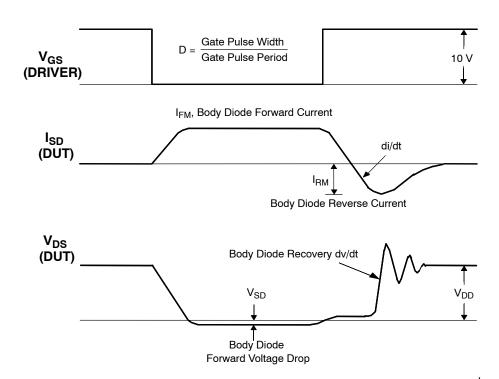
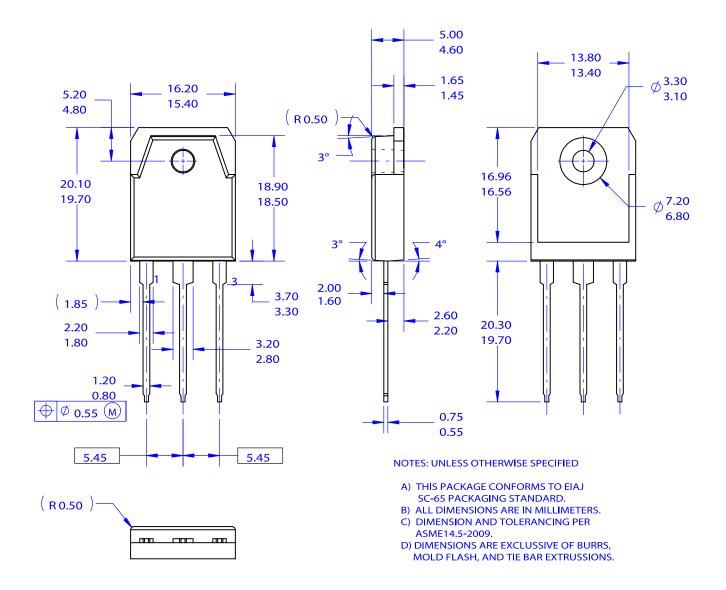


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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